

November 2013

# FGL35N120FTD 1200 V, 35 A Field Stop Trench IGBT

### **Features**

- Field Stop Trench Technology
- High Speed Switching
- Low Saturation Voltage: V<sub>CE(sat)</sub> = 1.68 V @ I<sub>C</sub> = 35 A
- High Input Impedance

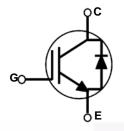
## **Applications**

· Solar Inverter, UPS, Welder, PFC

## **General Description**

Using advanced field stop trench IGBT technology, Fairchild's 1200V trench IGBTs offer the optimum performance for hard switching application such as solar inverter, UPS, welder applications.





## **Absolute Maximum Ratings**

Symbol	Description		Ratings	Unit
V <sub>CES</sub>	Collector to Emitter Voltage		1200	V
$V_{GES}$	Gate to Emitter Voltage		± 25	V
	Collector Current	@ T <sub>C</sub> = 25°C	70	А
l <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 100°C	35	А
I <sub>CM (1)</sub>	Pulsed Collector Current	@ T <sub>C</sub> = 25°C		
	Diode Continuous Forward Current	@ T <sub>C</sub> = 25°C	80	A
I <sub>F</sub>	Diode Continuous Forward Current	$@ T_C = 100^{\circ}C$	40	A
$P_{D}$	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	368	W
. р	Maximum Power Dissipation	$@ T_C = 100^{\circ}C$	147	W
T <sub>J</sub>	Operating Junction Temperature		-55 to +150	°C
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 second	s	300	°C

Notes:
1: Repetitive rating: Pulse width limited by max. junction temperature

### **Thermal Characteristics**

Symbol	Parameter	Max.	Unit
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	0.34	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	0.9	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	25	°C/W

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGL35N120FTDTU	FGL35N120FTD	TO-264	Tube	N/A	N/A	30

# Electrical Characteristics of the IGBT $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	$V_{GE} = 0 \text{ V}, I_{C} = 250 \mu A$	1200	-	-	V
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}$ , $V_{GE} = 0$ V	-	-	1	mA
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	-	±250	nA
On Charac	teristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	$I_C = 35 \text{ mA}, V_{CE} = V_{GE}$	3.5	6.2	7.5	V
		I <sub>C</sub> = 35 A, V <sub>GE</sub> = 15 V	-	1.68	2.2	V
V <sub>CE(sat)</sub>	Collector to Emitter Saturation Voltage	$I_C = 35 \text{ A}, V_{GE} = 15 \text{ V},$ $T_C = 125^{\circ}\text{C}$	-	2.0	-	V
Dynamic C	haracteristics					
C <sub>ies</sub>	Input Capacitance		-	5090	-	pF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$	-	180	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	f = 1 MHz	-	95	-	pF
Switching	Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time		-	34	-	ns
t <sub>r</sub>	Rise Time	$V_{CC} = 600 \text{ V}, I_{C} = 35 \text{ A},$ $R_{G} = 10 \Omega, V_{GE} = 15 \text{ V},$ Inductive Load, $T_{C} = 25^{\circ}\text{C}$	-	63	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	172	-	ns
t <sub>f</sub>	Fall Time		-	107	-	ns
E <sub>on</sub>	Turn-On Switching Loss		-	2.5	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	1.7	-	mJ
E <sub>ts</sub>	Total Switching Loss		-	4.2	-	mJ
t <sub>d(on)</sub>	Turn-On Delay Time		-	33	-	ns
t <sub>r</sub>	Rise Time		-	66	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>CC</sub> = 600 V, I <sub>C</sub> = 35 A,	-	180	-	ns
t <sub>f</sub>	Fall Time	$R_G = 10 \Omega$ , $V_{GE} = 15 V$ ,	-	146	-/	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 125°C	-	3.1	-	mJ
E <sub>off</sub>	Turn-Off Switching Loss		-	2.1	-	mJ
E <sub>ts</sub>	Total Switching Loss		-	5.2	- //	mJ
Qg	Total Gate Charge		-	210	-	nC
Q <sub>ge</sub>	Gate to Emitter Charge	$V_{CE} = 600 \text{ V}, I_{C} = 35 \text{ A},$ $V_{GE} = 15 \text{ V}$	-	42	- \	nC
Q <sub>gc</sub>	Gate to Collector Charge	vGE = 15 v	-	101	-	nC

# Electrical Characteristics of the Diode $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Condition	าร	Min.	Тур.	Max	Unit
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> = 35 A	$T_{\rm C} = 25^{\rm o}{\rm C}$	-	2.7	3.4	V
FIM	2.000 r ormana romage	1 <sub>F</sub> = 50 / t	$T_{\rm C} = 125^{\rm o}{\rm C}$	-	2.5	-	] '
t <sub>rr</sub>	Diode Reverse Recovery Time		$T_C = 25^{\circ}C$	-	337	-	ns
11	Diede Nevelee Nesevely Time	$I_F = 35 \text{ A},$ $di_F/dt = 200 \text{ A}/\mu\text{s}$	$T_{\rm C} = 125^{\rm o}{\rm C}$	-	520	-	
Irr	Diode Peak Reverse Recovery		$T_C = 25^{\circ}C$	-	7.6	-	Α
	Current		$T_{\rm C} = 125^{\rm o}{\rm C}$	-	12.9	-	, ,
Q <sub>rr</sub>	Diode Reverse Recovery Charge		$T_{\rm C} = 25^{\rm o}{\rm C}$	-	1292	-	nC
α <sub>II</sub>	Blodd Novolod Noddvely Charge		$T_{\rm C} = 125^{\rm o}{\rm C}$	1	3377	-	

Figure 1. Typical Output Characteristics

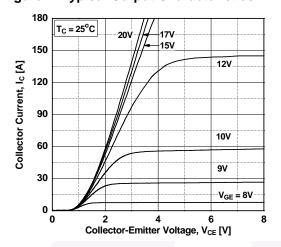


Figure 3. Typical Saturation Voltage Characteristics

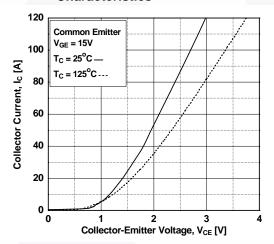
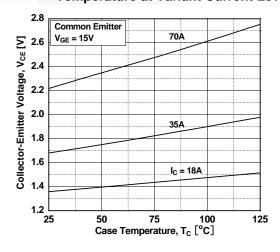


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level



**Figure 2. Typical Output Characteristics** 

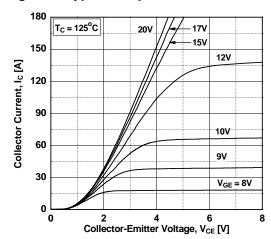


Figure 4. Transfer Characteristics

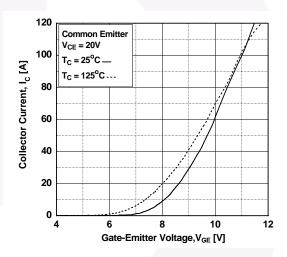


Figure 6. Saturation Voltage vs. V<sub>GE</sub>

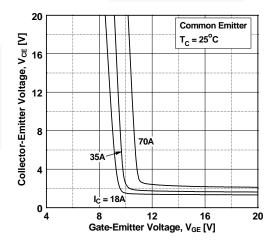


Figure 7. Saturation Voltage vs. V<sub>GE</sub>

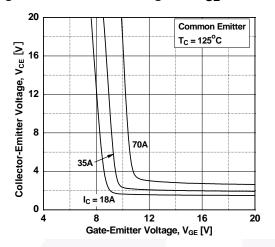


Figure 9. Capacitance Characteristics

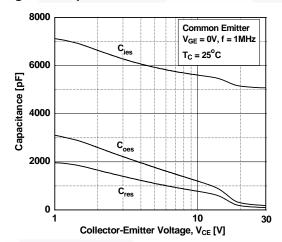


Figure 11. SOA Characteristics

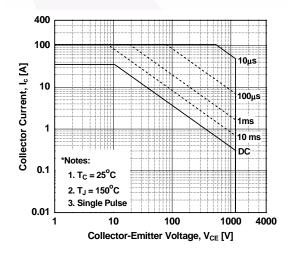


Figure 8. Load Current vs. Frequency

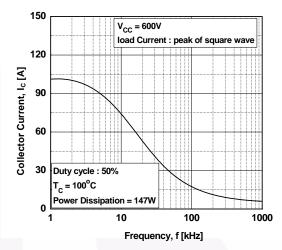


Figure 10. Gate Charge Characteristics

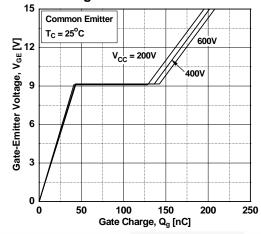


Figure 12. Turn-on Characteristics vs.
Gate Resistance

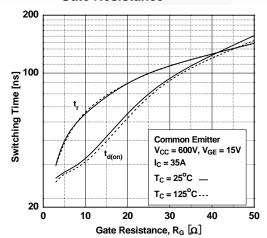


Figure 13. Turn-off Characteristics vs.
Gate Resistance

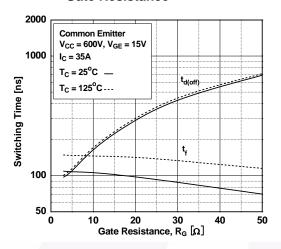


Figure 15. Turn-off Characteristics vs. Collector Current

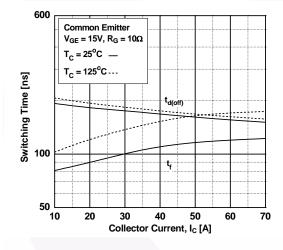


Figure 17. Switching Loss vs. Collector Current

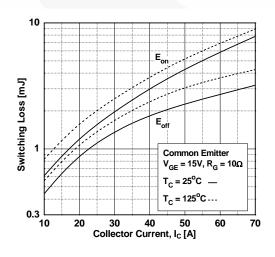


Figure 14. Turn-on Characteristics vs. Collector Current

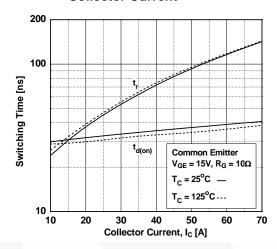


Figure 16.Switching Loss vs. Gate Resistance

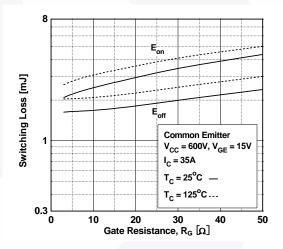


Figure 18. Turn off Switching SOA Characteristics

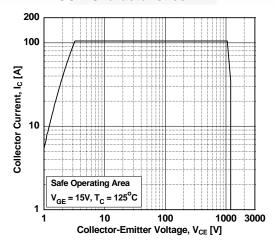


Figure 19. Forward Characteristics

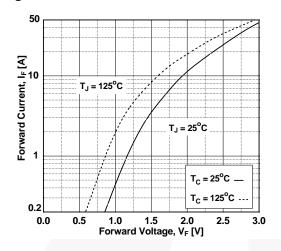


Figure 20. Reverse Recovery Current

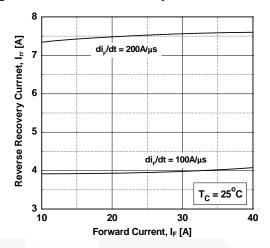


Figure 21. Stored Charge

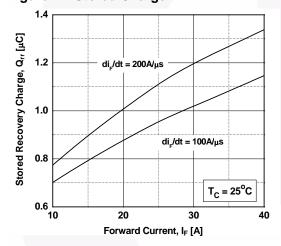


Figure 22. Reverse Recovery Time

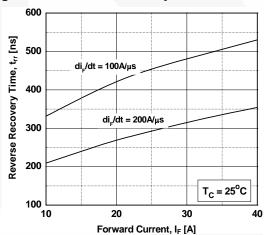
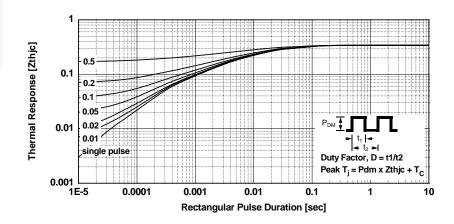


Figure 23. Transient Thermal Impedance of IGBT



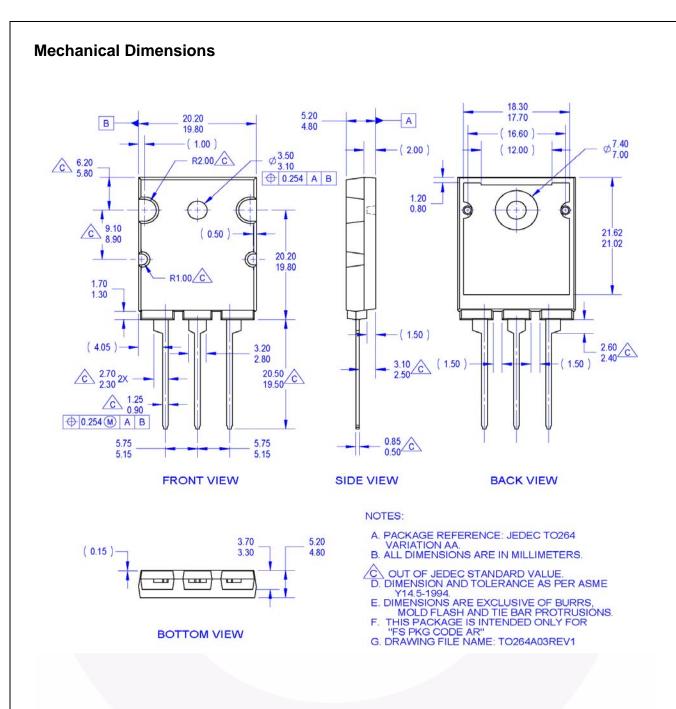


Figure 24. TO-264 3L - 3LD; TO264; MOLDED; JEDEC VARIATION AA

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